

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number:	SUP53P06-20-GE3
Manufacturer:	Vishay Siliconix
Package:	Please confirm with sales
Availability:	Please confirm with sales

Product Page:

<https://antrexco.com/product/details/vishay-siliconix/sup53p06-20-ge3.html>

Request a Quote:

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Contact Information

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Website: <https://antrexco.com>

Quality & Trust

New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

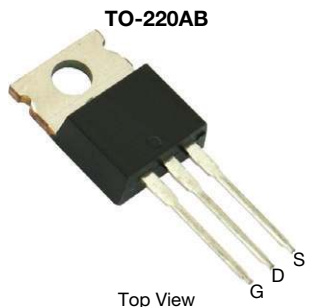
Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

P-Channel 60 V (D-S) MOSFET



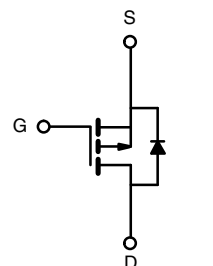
FEATURES

- TrenchFET® power MOSFET
- 100 % UIS tested
- Material categorization:
for definitions of compliance please see
www.vishay.com/doc?99912


RoHS
COMPLIANT

APPLICATIONS

- Load switch



P-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	-60
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10$ V	0.0195
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.0250
Q_g typ. (nC)	76
I_D (A) ^a	-53
Configuration	Single

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	SUP53P06-20-E3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	-60	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	-53 ^a
		$T_C = 70$ °C	-46.8
		$T_A = 25$ °C	9.2 ^b
		$T_A = 70$ °C	-8.1 ^b
Pulsed drain current	I_{DM}	-150	A
Avalanche current pulse	I_{AS}	-45	A
Single pulse avalanche energy	E_{AS}	101	mJ
Continuous source-drain diode current	I_S	$T_C = 25$ °C	69 ^a
		$T_A = 25$ °C	2.1 ^b
Maximum power dissipation	P_D	$T_C = 25$ °C	104.2 ^a
		$T_C = 70$ °C	66.7 ^a
		$T_A = 25$ °C	3.1 ^b
		$T_A = 70$ °C	2 ^b
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	R_{thJA}	33	40	°C/W
Maximum junction-to-case	R_{thJC}	0.98	1.2	°C/W

Notes

a. Based on $T_C = 25$ °C



b. Surface mounted on 1" x 1" FR4 board

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-60	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = -250 μA	-	68	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	-5.2	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-1	-	-3	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V	-	-	-1	μA
		V _{DS} = -60 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	
On-state drain current ^a	I _{D(on)}	V _{DS} = -5 V, V _{GS} = -10 V	-120	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -10 V, I _D = -30 A	-	0.0160	0.0195	Ω
		V _{GS} = -4.5 V, I _D = -20 A	-	0.0200	0.0250	
Forward transconductance ^a	g _{fs}	V _{DS} = -15 V, I _D = -50 A	20	-	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} = -25 V, V _{GS} = 0 V, f = 1 MHz	-	3500	-	pF
Output capacitance	C _{oss}		-	390	-	
Reverse transfer capacitance	C _{rss}		-	290	-	
Total gate charge	Q _g	V _{DS} = -30 V, V _{GS} = -10 V, I _D = -55 A	-	76	115	nC
		V _{DS} = -30 V, V _{GS} = -4.5 V, I _D = -55 A	-	38	60	
Q _{gs}	-		16	-		
Q _{gd}	-		19	-		
Gate resistance	R _g	f = 1 MHz	-	5.2	-	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = -2 V, R _L = 2 Ω I _D ≡ -10 A, V _{GEN} = -10 V, R _g = 1 Ω	-	10	15	ns
Rise time	t _r		-	7	15	
Turn-off delay time	t _{d(off)}		-	70	110	
Fall time	t _f		-	40	60	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-69	A
Pulse diode forward current ^a	I _{SM}		-	-	-150	
Body diode voltage	V _{SD}	I _S = -30 A	-	-1	-1.5	V
Body diode reverse recovery time	t _{rr}	I _F = -50 A, di/dt = 100 A/μs, T _J = 25 °C	-	45	68	ns
Body diode reverse recovery charge	Q _{rr}		-	59	120	nC
Reverse recovery fall time	t _a		-	29	-	ns
Reverse recovery rise time	t _b		-	16	-	

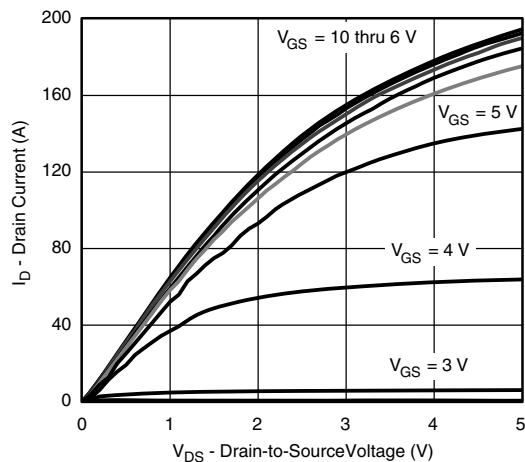
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

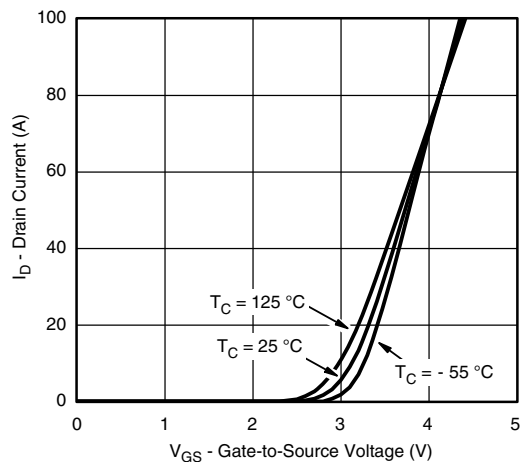
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



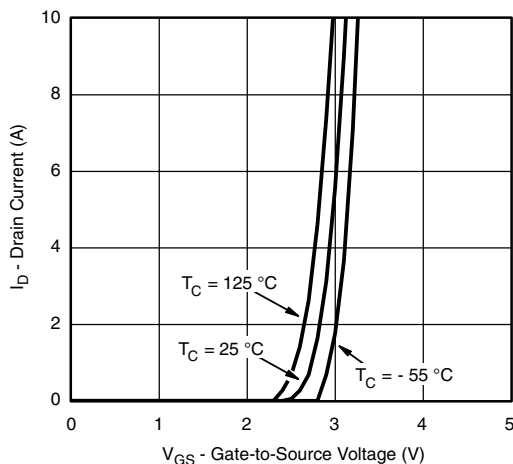
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



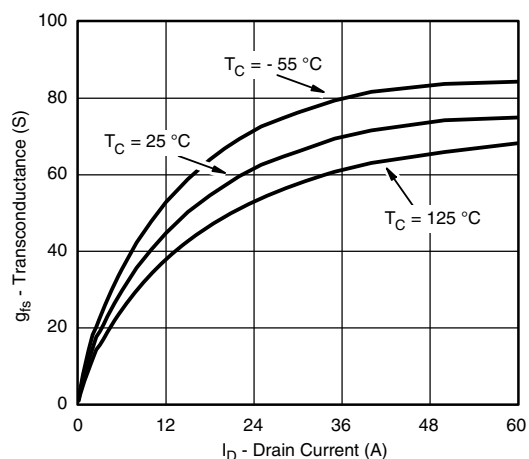
Output Characteristics



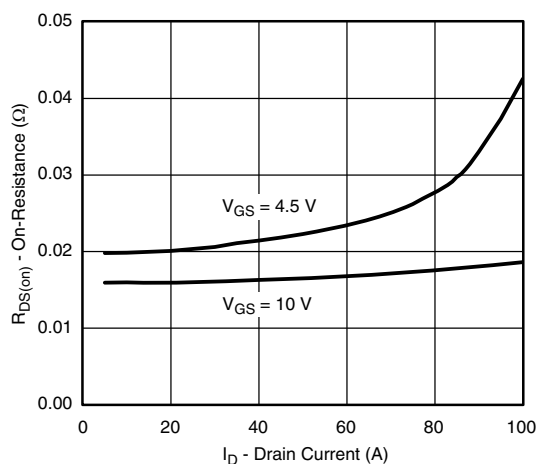
Transfer Characteristics



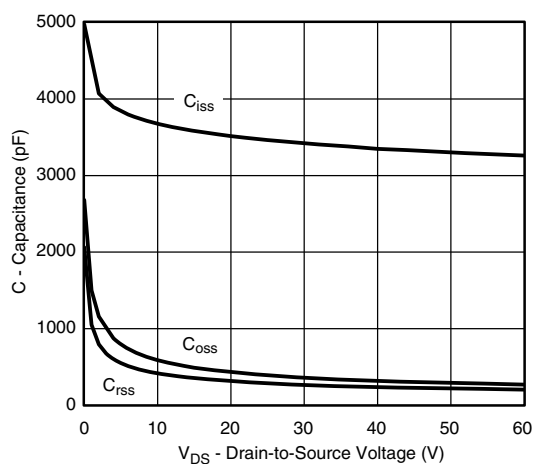
Transfer Characteristics



Transconductance



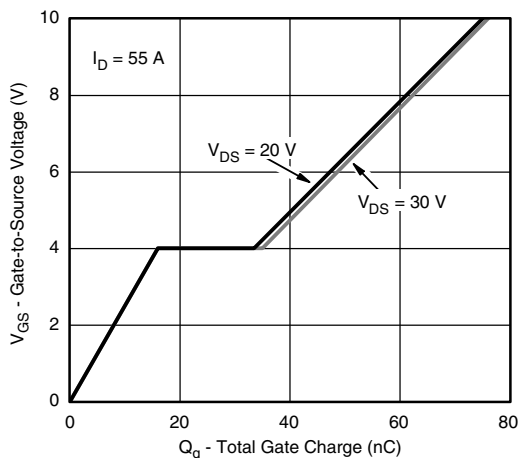
On-Resistance vs. Drain Current



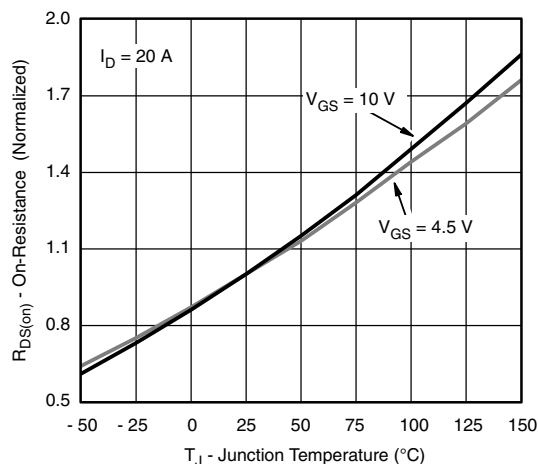
Capacitance



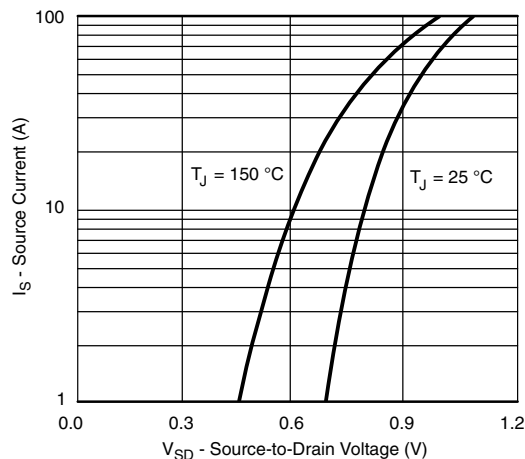
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



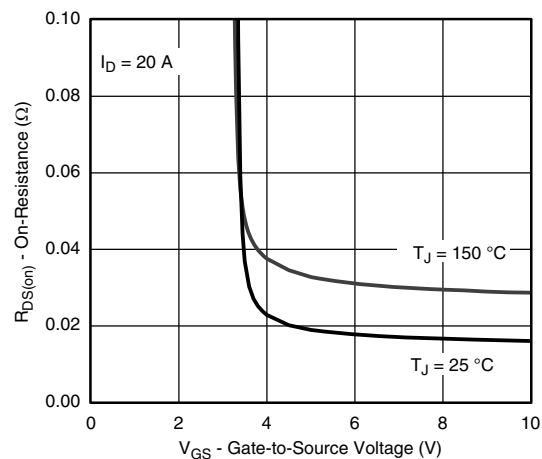
Gate Charge



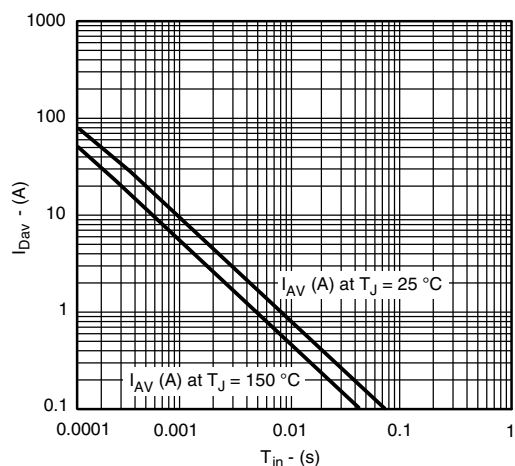
On-Resistance vs. Gate-to-Source Voltage



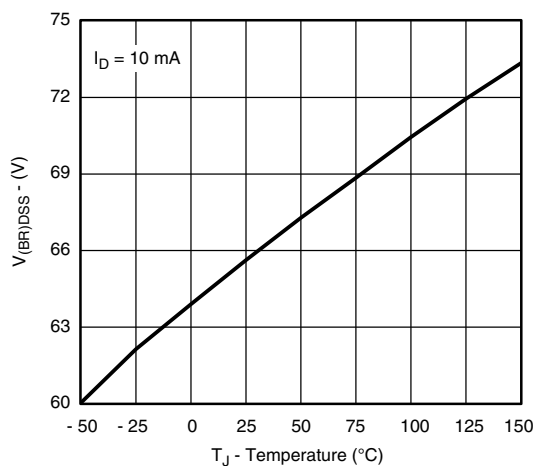
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



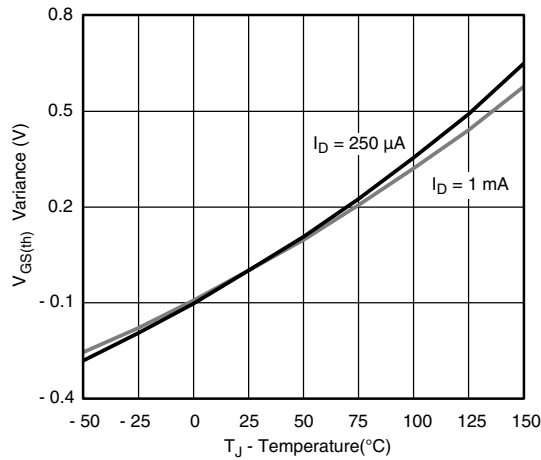
Single Pulse Avalanche Current Capability vs. Time



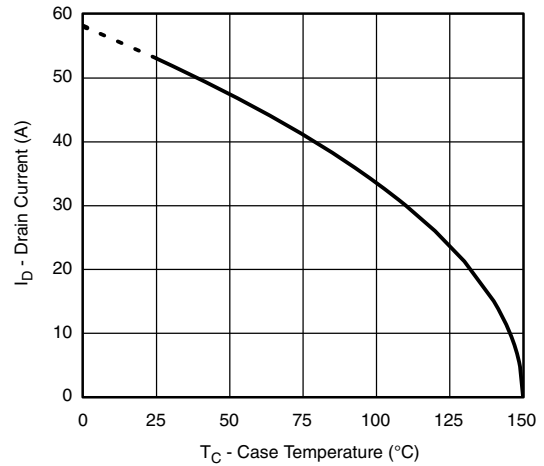
Drain-Source Breakdown Voltage vs. Junction Temperature



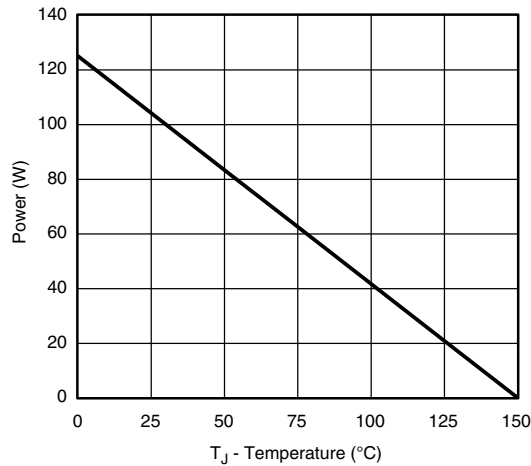
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



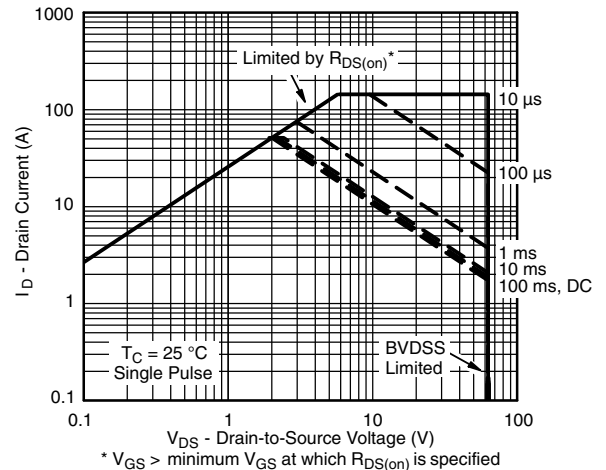
Threshold Voltage



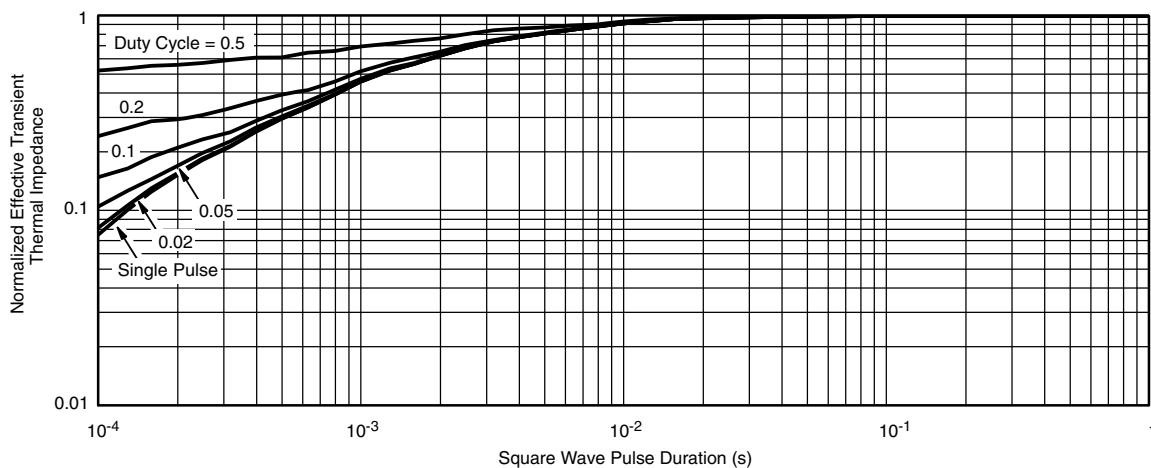
Max. Drain Current vs. Case Temperature



Power Derating, Junction-to-Case



Safe Operating Area, Junction-to-Case

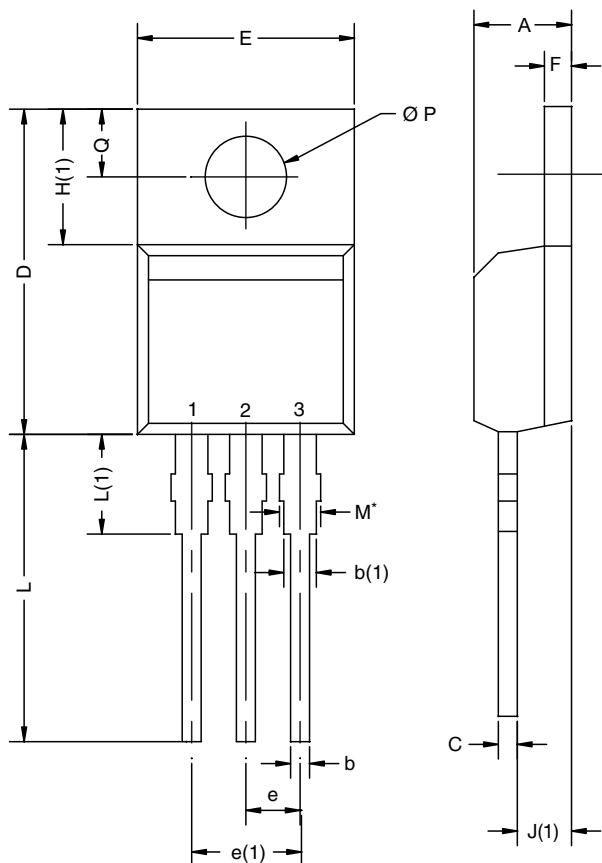


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68633.



TO-220AB

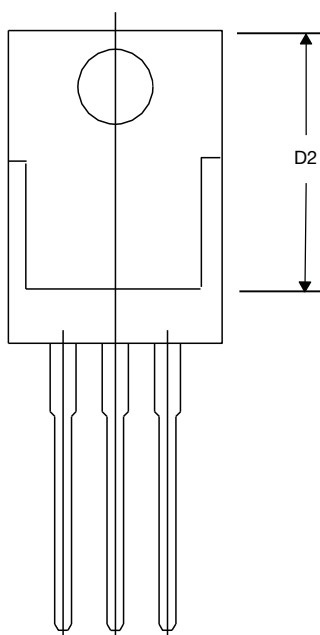


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: T14-0413-Rev. P, 16-Jun-14
DWG: 5471

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM





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